

CALENDAR

Upcoming: January 7–9 North American Perpendicular Magnetic Recording Conf; March 4–6 Advanced Packaging Materials; April 1–6 MRS Spring Meeting, MRS.

To list an event in the Calendar, contact J. Meiksin, Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3004 ext. 522; fax 724-779-8313; bulletin@mrs.org.

MRS, A-MRS, C-MRS, E-MRS, MRS-A, MRS-I, MRS-J, MRS-K, MRS-R, MRS-S, MRS-T, M-MRS, or IUMRS at the end of an entry indicates sponsorship or co-sponsorship of an event by the International Union of Materials Research Societies or one of its adhering bodies. "Endorsed" identifies events endorsed by MRS.

▼ identifies a new or revised entry this month.

See the September 2001 MRS BULLETIN for November 2001 Calendar entries.

DECEMBER 2001

2–5 Niobium Conf., *Orlando, FL*. D.G. Howden, 3285 Wilson Rd., P.O. Box 544, Sunbury, OH 43074-0544; fax 740-965-2366; e-mail niobium2001@worldnet.att.net.

3–4 ▼ 3rd Conf. on Controlled Polymer Synthesis—New Approaches in Applications and Processes, *Cambridge, MA*. The Knowledge Foundation, 18 Webster St., Brookline, MA 02446; 617-232-7400; fax 617-232-9171; e-mail custserv@knowledgefoundation.com; www.knowledgefoundation.com.

3–5 2nd Intl. Symposium on Polyimides and Other High Temperature Polymers, *Newark, NJ*. R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/polyim2.htm.

3–6 Australasian Conf. on Optics and Laser Spectroscopy, *Brisbane, Queensland, Australia*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

3–7 10th Intl. Congress of Fracture, *Honolulu, HI*. A. Hill, ICF10 Congress Secretariat, Elsevier Science, The Boulevard, Langford Lane, Kidlington, Oxford OX5 1GB, UK; 44-1865-843-643; fax 44-1865-843-958; e-mail a.richardson@elsevier.co.uk; www.elsevier.com.

3–7 Pacific Polymer Federation Conf., *Oaxaca City, Mexico*. T. Ogawa, Inst. de Investigaciones en Materiales, UNAM, Ap. 70-360, CU, Coyoacan, Mexico DF 04510, Mexico; 52-5-622-4583; fax 52-5-616-1201; e-mail ogawa@servidor.unam.mx; www.chem.umr.edu/~poly/poly_spon.html.

5–7 Intl. Semiconductor Device Research Symposium, *Georgetown, Washington, DC*. A. Iliadis, ISDRS '01 Symposium Chair, Dept. of Electrical and Computer Engineering, Univ. of Maryland, College Park, MD 20742; e-mail agis@eng.umd.edu; www.ece.umd.edu/ISDRS_2001.

5–8 3rd Intl. Symposium on Environmental Hydraulics, *Tempe, AZ*. R. Rankin, ISEH 2001 Secretary, Arizona State Univ., Dept. of Mechanical and Aerospace Engineering, P.O. Box 876106, Tempe, AZ 85287-6106; 480-965-3207; fax 480-965-1384; e-mail iseh@enpop2.eas.asu.edu; www1.eas.asu.edu/~iseh2001.

6–7 8th Intl. Symposium on Metallized Plastics, *Newark, NJ*. R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/metalplas8.htm.

11–15 4th Pacific Rim Intl. Conf. on Advanced Materials and Processing, *Honolulu, HI*. S. Hanada, Tohoku Univ., Inst. for Materials Research, Katahira 2-1-1, Aoba-ku, Sendai 980-8577, Japan; 81-22-215-2115; fax 81-22-215-2116; e-mail ccpricm4@imr.tohoku.ac.jp.

11–15 11th Intl. Workshop on the Physics of Semiconductor Devices, *New Delhi, India*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

17–19 Intl. Symposium on Microelectronics and MEMS, *Adelaide, Australia*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

JANUARY 2002

6–11 13th Intl. Conf. on Ternary and Multinary Compounds, *Dead Sea, Israel*. D. Cahen, Dept. of Materials and Interfaces, Weizmann Inst. of Science, Rehovoth, Israel 76100; 972-0-89-34-2246; fax 972-0-89-34-4139; e-mail david.cahen@weizmann.ac.il; www.weizmann.ac.il/material.

6–12 Winter Conf. on Plasma Spectrochemistry, *Scottsdale, AZ*. R. Barnes, ICP Information Newsletter, Inc., P.O. Box 666, Hadley, MA 01003-0666; 413-256-8942; fax 413-256-3746; e-mail winterconf@chem.umass.edu; www.chem.umass.edu/WinterConf2002.

7–9 ▼ 1st North American Perpendicular Magnetic Recording Conf., *Coral Gables, FL*. NAPMRC Secretariat, Dept. of Physics, Univ. of Miami, P.O. Box 248046, Coral Gables, FL 33124; fax 419-791-3337; e-mail info@napmrc.org; www.napmrc.org. Endorsed.

13–17 Conf. on Thermal Challenges in Next Generation Electronic Systems, *Santa Fe, NM*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

13–18 26th Annual Intl. Conf. on Advanced Ceramics and Composites, *Cocoa Beach, FL*. Technical Program Coordinator, American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; fax 614-794-5882; e-mail jdavis@acers.org.

21–24 ▼ Thermal Solutions® Infrared Thermography Conf., *Orlando, FL*. L. Bond, Snell Infrared, P.O. Box 6, Montpelier, VT 05601-0006; 800-636-9820; fax 802-223-0460; e-mail info@snellinfrared.com; www.thermal-solutions.org.

23–25 2nd Intl. Colloquium on Modeling of Glass Forming and Tempering, *Valenciennes, France*. P. Moreau, Colloquium Organizer, M.G.F.T. 2002, L.A.M.I.H/L.G.M., Univ. de Valenciennes et du Hainaut-Cambrésis, 59313 Valenciennes Cedex 9, France; 33-3-27-51-13-84; fax 33-3-27-51-13-17; e-mail philippe.moreau@univ-valenciennes.fr; www.univ-valenciennes.fr.

28–31 ▼ Intl. Exhibition and Seminar on Energy and Environment in Cement, Construction, and Allied Sectors, *New Delhi, India*. Director General, Intl. Exhibition and Seminar on Energy and Environment in Cement, Construction, and Allied Sectors, Natl. Council for Cement and Building Materials, A-135, Defence Colony, New Delhi 110 024, India; 91-129-5241963; fax 91-129-5242100; e-mail nccbm@giasd101.vsnl.net.in; www.cementresearch.com.

28–1 ▼ AAPS Workshop on Critical Issues in the Design and Application of Polymeric Biomaterials in Drug Delivery, *Arlington, VA*. American Association of Pharmaceutical Scientists, 2107 Wilson Blvd., Ste. 700, Arlington, VA 22201-3046; 703-243-2800; fax 703-243-9650; e-mail aaps@aaps.org; www.aapspharmaceutica.com.

FEBRUARY 2002

1–3 Intl. Conf. on Advances in Materials and Materials Processing, *Kharagpur, India*. Dept. of Metallurgical and Materials Engineering, Indian Inst. of Technology, Kharagpur 721 302, India; 91-3222-82280; fax 91-3222-55303; e-mail icamp@metal.iitkgp.ernet.in.

3–6 OSA Meeting on Advanced Solid-State Lasers, *Québec City, Canada*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., NW, Washington, DC 20036-1023; 202-416-1907; fax 202-416-6140; e-mail cust.serv@osa.org; www.osa.org/mtg_conf.

7–10 OSA Meeting on Laser Applications to Chemical and Environmental Analysis, *Boulder, CO*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., NW, Washington, DC 20036-1023; 202-416-1907; fax 202-416-6140; e-mail cust.serv@osa.org; www.osa.org/mtg_conf.

17–21 TMS Annual Meeting, *Seattle, WA*. TMS, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail weissp@tms.org; www.tms.org/meetings.

MARCH 2002

2–3 Conf. on Film Formation: Mechanism, Properties, and Characterization, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org.

2–3 Conf. on Polymer Degradation and Stabilization, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org.

4–6 4th Biennial Conf. on Polymer Stabilizers and Modifiers, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org.

4–6 ▼ Advanced Packaging Materials—Processes, Properties and Interfaces, *Stone Mountain, GA*. Dr. Jianmin Qu, Dept. of Metallurgical and Materials Engineering, Indian Inst. of Technology, Kharagpur 721 302, India; 91-3222-82280; fax 91-3222-55303; e-mail icamp@metal.iitkgp.ernet.in.

4–6 Conf. on Film Formation: Science and Technology, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org.

4–7 Manufacturing Applications Expo Intl.: AWS Welding Show and PMA METALFORM Expo, *Chicago, IL*. American Welding Society, 550 NW LeJeune Rd., Miami, FL 33126; 800-443-9353; fax 305-443-7559; e-mail www.aws.org; www.maxinternational.com.

7–8 Conf. on Advanced Microelectronic Manufacturing and Nanotechnologies, *Santa Clara, CA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

11–13 IMAPS Intl. Conf. on Advanced Packaging and Systems, *Reno, NV*. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

APRIL 2002

11-13 Intl. Conf. on High-Performance Structures and Composites, *Seville, Spain*. Conf. Secretariat, HPSC 2002, Wessex Inst. of Technology, Ashurst Lodge, Ashurst, Southampton, SO40 7AA, UK; 44-2380-293223; fax 44-2380-292853; e-mail shanley@wessex.ac.uk; www.wessex.ac.uk/conferences/2002/hpsc02.

11-15 ▼ 3rd Intl. Conf. on Porous Semiconductors—Science and Technology, *Tenerife, Spain*. E. Matveeva (PSST-2002), Dept. de Ingeniería Mecánica y de Materiales, Univ. Politécnica de Valencia, Camino de Vera s/n, 46022 Valencia, Spain; 34-96-387-7620; fax 34-96-387-7629; e-mail psst-2002@upvnet.upv.es; www.upv.es/psst_2002.

12-14 Chemtex and Corrosion Conf., *Dubai, United Arab Emirates*. Intl. Expo-Consults L.L.C., P.O. Box 50006, Dubai, United Arab Emirates; 971-4-3435777; fax 971-4-3436115; e-mail iec@emirates.net.ae; www.expo-consults.com.

17-20 7th Intl. Multidisciplinary Conf. on Complexity and Fractals in the Sciences, *Granada, Spain*. M.M. Novak, School of Mathematics, Kingston Univ., Penrhyn Rd., Surrey KT1 2EE, UK; www.kingston.ac.uk/fractal.

17-21 Conf. on Smart Structures and Materials, *San Diego, CA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

18-22 APS March Meeting, *Indianapolis, IN*. American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

18-22 Intl. Solvent Extraction Conf., *Cape Town, South Africa*. Conf. Secretariat, Private Bag X3015, Randburg 2125, South Africa; 27-11-709-4255; fax 27-11-709-4326; e-mail isec2002@mintek.co.za; www.isec2002.org.za.

27-28 ▼ Forum on Materials and Society: From Research to Manufacturing, *Washington, DC*. Natl. Materials Advisory Board, 2101 Constitution Ave. N.W., Harris Bldg., Rm. 262, Washington, DC 20007; 202-334-3505; fax 202-334-3718; e-mail nmab@nas.edu; www4.nas.edu.

1-5 **MRS Spring Meeting**, *San Francisco, CA*. Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS**.

3-5 Intl. Conf. on High-Density Interconnect and Systems Packaging, *Santa Clara, CA*. Intl. Microelectronics And Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

8-10 Intl. Conf. on Metal Powder Deposition for Rapid Manufacturing, *San Antonio, TX*. S.E. Leatherman, Technical Programs Mgr., Metal Powder Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail leatherm@mpif.org; www.mpif.org.

9-11 Materials Congress 2002, *London, UK*. V. Morrison, IOM Communications, 1 Carlton House Terrace, London SW1Y 5DB, UK; 44-20-7451-7340; fax 44-20-7839-2289; www.materials.org.uk/congress2002/intro.htm.

13-18 ▼ 45th SVC Technical Conf., *Lake Buena Vista, FL*. Society of Vacuum Coaters, 71 Pinon Hill Place N.E., Albuquerque, NM 87122-1914; 505-856-7188; fax 505-856-6716; e-mail svcinfo@svc.org; www.svc.org.

17-19 IMAPS Intl. Conf. on Electronics Packaging and 16th Microelectronics Show, *Tokyo, Japan*. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

20-23 ▼ APS April Meeting, *Albuquerque, NM*. American Physical Society, 1 Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

22-25 ▼ Intl. Conf. on Computational Nano Science, and Modeling and Simulation of Microsystems, *San Juan, Puerto Rico*. ICCN-MSM, 696 San Ramon Valley Blvd., Ste. 423, Danville, CA 94526-4022; 925-743-9466; fax 509-696-6416; e-mail wenning@cr.org; www.cr.org/MSM2002/register.html.

28-1 104th ACerS Annual Meeting, *St. Louis, MO*. The American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 614-899-6109; e-mail info@acers.org; www.ceramics.org.

29-30 IMAPS Technology Workshop on Ceramic Applications for Microwave and Photonic Packaging, *Providence, RI*. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

29-2 Intl. Conf. on Characterization and Metrology for ULSI Technology, *Gaithersburg, MD*. L. Printz, NIST, Gaithersburg, MD 20899; e-mail lori.printz@nist.gov; www.eeel.nist.gov/812/conference. **Endorsed**.

MAY 2002

5-8 ▼ 8th Magneto-Optical Recording Intl. Symposium, *Bénodet, Brittany, France*. MORIS'2002 Secretariat, c/o N. Keller, LMOV—Univ. of Versailles/CNRS, 45 Ave. des Etats-Unis, 78035 Versailles Cedex, France; 33-139-25-4670; fax 33-139-25-4652; e-mail moris2002@physique.uvsq.fr; www.univ-brest.fr/moris2002.

6-7 Intl. Conf. on Functionally Graded Materials, *Denver, CO*. S. Leatherman, Technical Programs Mgr., Metal Powder Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail leatherm@mpif.org; www.mpif.org.

12-16 ▼ SAMPE Conf. on Affordable Material Technology—Platform to Global Value and Performance, *Long Beach, CA*. D. Weaver, SAMPE Business Office, P.O. Box 2459, Covina, CA 91722; 626-331-0616; fax 626-332-8929; e-mail dweaveribo@cs.com; www.sampe.org.

12-17 201st Meeting of the Electrochemical Society, *Philadelphia, PA*. The Electrochemical Society, 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org.

21-26 ▼ Intl. Conf. on Nuclear Structure: Mapping the Triangle, *Grand Teton Natl. Park, WY*. L. Riedinger, Oak Ridge Natl. Lab.; 865-574-4321; fax 865-574-8225; e-mail triangle@ornl.gov; http://wnsl.physics.yale.edu/icns2002.

24-28 ▼ APS Div. of Particles and Fields Meeting, *Williamsburg, VA*. DPF2002, Dept. of Physics, College of William and Mary, Williamsburg, VA 23187-8795; 757-221-3538; fax 757-221-3540; e-mail dpf2002@physics.wm.edu; http://www.dpf2002.org.

27-29 7th European Symposium on Polymer Blends, *Lyon-Villeurbanne, France*. Secretariat, 7th European Symposium on Polymer Blends, Lab. des Matériaux Macromoléculaires, Bat J. Verne, INSA Lyon, 20 Ave. Albert Einstein, 69621, Villeurbanne Cedex, France; 33-4-72-43-8527; e-mail polymerblends@insa-lyon.fr; www.insa-lyon.fr/polymer_blends/index.htm.

JUNE 2002

3-7 ▼ 9th Intl. Conf. on Muon Spin Rotation, Relaxation, and Resonance, *Williamsburg, VA*. C.E. Stronach, Conf. Chair, Physics Dept., P.O. Box 9325, Virginia State Univ., Petersburg, VA 23806; 804-524-5915; fax 804-524-5439; e-mail cstronac@vsu.edu; http://muon.physics.wm.edu/~musr2002.

10-14 8th Intl. Conf. on Electronic Materials, *Xi'an, China*. J. Cheng; 86-10-6894-4280; fax 86-10-6842-8640; e-mail cmrsec@public.bta.net.cn; www.c-mrs.org.cn/icem2002. **C-MRS**.

16-18 European IMAPS Symposium, *Cracow, Poland*. Intl. Microelectronics And Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

16-20 Intl. Cryogenic Materials Conf., *Xi'an, China*. Y. Feng, Northwest Inst. for Non-ferrous Metal Research, P.O. Box 51, Xi'an, Shaanxi 710016, China; 86-29-623-1079; fax 86-29-623-1103; e-mail smrc@pub.xaonline.com.

16-21 Powder Metallurgy and Particulate Materials World Congress, *Orlando, FL*. S. Leatherman, Metal Powder Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail leatherm@mpif.org; www.mpif.org.

17-20 1st Intl. Conf. on Multiscale Materials Modeling, *London, UK*. MMM Local Organising Committee, Dept. of Materials, Queen Mary, Univ. of London, London E1 4NS, UK; 44-20-7882-5159; fax 44-20-8981-9804; e-mail x.guo@qmw.ac.uk; www.multiscalemodelling.com.

17-21 ▼ **E-MRS Spring Meeting**, *Strasbourg, France*. E-MRS, 23 rue du Loess, B.P. 20, 67037 Strasbourg Cedex 02, France; 33-3-8810-6372; fax 33-3-8810-6343; e-mail emrs@phase.c-strasbourg.fr; www-emrs.c-strasbourg.fr. **E-MRS**.

23-26 Intl. Conf. on Thermomechanical Processing, *Sheffield, UK*. Thermomechanical Processing: Mechanics, Microstructure, and Control, c/o IMPETUS Admin. Office, Univ. of Sheffield, Sir Frederick Mappin Bldg., Mappin St., Sheffield S1 3JD, UK; 44-114-222-6018; fax 44-114-222-6015; e-mail tpmmc@sheffield.ac.uk; http://dyn052176.shef.ac.uk/conference_2002.

23-27 ▼ 6th Intl. Conf. on Computer Simulation of Radiation Effects in Solids, *Dresden, Germany*. COSIRES2002, c/o Forschungszentrum Rossendorf e.V., Inst. of Ion Beam Physics and Materials Research, P.O. Box 510119, 01314 Dresden, Germany; fax 48-351-260-3285; e-mail COSIRES2002@fz-rossendorf.de; www.fz-rossendorf.de/FWI/COSIRES2002.

23-28 11th Intl. Meeting on Lithium Batteries, *Monterey, CA*. IMLB 11 Conf. Secretariat, c/o The Electrochemical Society, Inc., 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org/meetings/011/mlb11.html.

26-28 Electronic Materials Conf., *Santa Barbara, CA*. TMS Meetings Services, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail mtgserv@tms.org; www.tms.org/meetings.

JULY 2002

1-5 Conf. on Coatings Science and Technology, *Athens, Greece*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org.

1-5 Intl. Conf. on Fuel Cells, *Lucerne, Switzerland*. European Fuel Cell Forum, P.O. Box 99, CH-5452 Oberrohrdorf, Switzerland; 41-56-496-7292; fax 41-56-496-4412; e-mail info@efcf.com; www.efcf.com.

7-12 7th Intl. Workshop on Positron and Positronium Chemistry, *Knoxville, TN*. S. Lantz, PPC7, Oak Ridge Natl. Lab., P.O. Box 2008, M.S. 6142, Oak Ridge, TN 37831; 865-574-4882; fax 865-574-8363; e-mail Sharon.Lantz@ornl.gov; www.ornl.gov/ppc.

14-18 13th Intl. Symposium on Transport Phenomena, *Victoria, BC, Canada*. S. Dost, ISTEP-13, Dept. of Mechanical Engineering, Univ. of Victoria, Victoria, BC, Canada V8W 3P6; 250-721-8898; fax 250-721-6294; e-mail istp13@uvic.ca; www.istp13.uvic.ca.

14-19 ▼ 10th Intl. Conf. on the Physics and Chemistry of Ice, *St. John's, Newfoundland, Canada*. Conf. Office, Rm. 315 Hatcher House, Memorial Univ. of Newfoundland, St. John's, NF Canada A1B 3P7; 709-737-7657; fax 709-737-3520; e-mail Stephen.Jones@nrc.ca; www.housing.mun.ca/conf/pci/.

14-19 CIMTEC Intl. Conf. on Materials and Technologies: 10th Intl. Ceramics Congress and 3rd Forum on New Materials, *Florence, Italy*. CIMTEC 2002 Secretariat, P.O. Box 174, 48018 Faenza, Italy; 39-546-22461; fax 39-546-664138; www.dinamica.it/cimtec.

14-19 Conf. on Polymer Colloids: Preparation and Properties of Aqueous Polymer Dispersions, *Irsee, Germany*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

17-19 Intl. Conf. on Smart Materials, Structures, and Systems, *Bangalore, India*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

21-26 4th World Congress on Particle Technology, *Sydney, Australia*. J. Hatte, Conf. Coordinator, ICMS Australasia Pty Ltd., Level 6, 2 Bridge St., Sydney NSW 2000, Australia; 61-2-9241-1478; fax 61-2-9251-3552; e-mail josie@icmsaust.com.au; www.wcpt4.com/.

21-26 8th Intl. Conf. on New Diamond Science and Technology, *Melbourne, Australia*. B. Hewitt, Conf. Mgmt., Old Physics Bldg., Univ. of Melbourne, Parkville 3010, Victoria, Australia; 61-3-8344-6389; fax 61-3-8344-6122; e-mail icndst-8@unimelb.edu.au; www.conferences.unimelb.edu.au/icndst-8.

22-25 ▼ Intl. Workshop on Nitride Semiconductors, *Aachen, Germany*. IWN 2002 Secretariat, Forschungszentrum Jülich GmbH, Conf. Service, 52425 Jülich, Germany; 49-24-6161-3833; fax 49-24-6161-5333; e-mail iwn2002@fz-juelich.de; www.fz-juelich.de/iwn2002.

29-2 26th Intl. Conf. on the Physics of Semiconductors, *Edinburgh, Scotland*. Conf. Dept., ICPS2002, Inst. of Physics, 76 Portland Place, London W1B 1NT, England; 44-20-7470-4800; fax 44-20-7470-4900; www.icps2002.org.

AUGUST 2002

4-9 ▼ Applied Superconductivity Conf.®, *Houston, TX*. Centennial Conferences, 4800 Baseline Rd., Ste. A-112, Boulder, CO 80303; 303-499-2299; fax 303-499-2599; e-mail asc@centennialconferences.com; www.ascinc.org.

18-23 Intl. Conf. on Electrophoretic Deposition: Fundamentals and Applications, *Banff, Canada*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

20-27 23rd Intl. Conf. on Low-Temperature Physics, *Hiroshima, Japan*. Japan Convention Services, Inc., LT23, Nippon Press Ctr., Bldg., 2-2-1, Uchisaiwaicho, Chiyodaku, Tokyo 100-0011, Japan; 81-3-3508-1214; e-mail lt23@convention.co.jp; www.issp.u-tokyo.ac.jp/lt23.

24-27 ▼ 3rd World Congress on Emulsions, *Lyon, France*. CME, 50 place Marcel Pagnol, 92100 Boulogne-Billancourt, France; 33-1-4761-7689; fax 33-1-4761-7465; e-mail alain.lecoroller@wanadoo.fr; http://wa157.lerelaisinternet.com/cme-emulsion.

25-29 Conf. on Fluid Particle Interactions, *Barga, Italy*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

25-30 ▼ 11th Intl. Conf. on Rapidly Quenched and Metastable Materials, *Oxford, UK*. P. Schumacher, Dept. of Materials, Oxford Univ., Parks Rd., Oxford OX1 3PH, UK; 44-1865-273769; fax 44-1865-273764; e-mail rq11@materials.ox.ac.uk; www.materials.ox.ac.uk/rq11.

28-31 2nd Intl. Mould & Die Making and Manufacturing Technology Exhibition for Asia, *Hong Kong*. Business and Industrial Trade Fairs Ltd., Unit 1223, HITEC, 1 Trademart Dr., Kowloon Bay, Hong Kong; 852-2865-2633; fax 852-2866-1770; e-mail enquiry@bitf.com.hk.

SEPTEMBER 2002

4-6 35th Intl. Symposium on Microelectronics, *Denver, CO*. Intl. Microelectronics And Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

8-12 6th Intl. Meeting on Magnetic Resonance in Porous Media, *Ulm, Germany*. www.uni-ulm.de/nmr/mrpm6/early_notification.htm.

9-13 ▼ 8th Intl. Conf. on Plasma and Surface Engineering, *Garmisch-Partenkirchen, Germany*. Arbeitskreis Plasmaoberflächentechnologie (PISE Germany), c/o. K. Reichel, VDI-Technologiezentrum, Graf-Recke-Str. 84, D-40239 Düsseldorf, Germany; 49-211-6214-567; fax 49-211-6214-484; e-mail akplasma@vdi.de; www.akplasma.org.

10-12 ▼ Intl. Conf. on Design and Nature: Comparing Design in Nature with Science and Engineering, *Udine, Italy*. G. Cossutta, Conf. Secretariat, Wessex Inst. of Technology, Ashurst Lodge, Ashurst, Southampton SO40 7AA, UK; 44-238-029-3223; fax 44-238-029-2853; e-mail gcossutta@wessex.ac.uk; www.wessex.ac.uk.

16-20 Intl. Conf. on Shot Peening, *Garmisch-Partenkirchen, Germany*. P. Schepp, Deutsche Gesellschaft für Materialkunde e.V., Hamburger Allee 26, D-60486 Frankfurt, Germany; 49-69-7917-750; fax 49-69-7917-733; e-mail shot-peening@dgm.de; www.dgm.de/shot-peening.

24-27 3rd World Congress on Emulsions, *Lyon, France*. CME, 50 Place Marcel Pagnol, 92100 Boulogne-Billancourt, France; 33-147-617-689; fax 33-147-617-465; e-mail alain.lecoroller@wanadoo.fr; www.cme-emulsion.com.

OCTOBER 2002

1-4 54th Pacific Coast Regional and ACerS Basic Science Div. Meeting, *Seattle, WA*. American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 619-899-6109; e-mail customersrvc@acers.org; www.ceramics.org.

6-10 TMS Fall Meeting, *Columbus, OH*. TMS Programming Dept., 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail ckobert@tms.org; www.tms.org.

12-15 ACerS Glass and Optical Materials Div. Meeting, *Pittsburgh, PA*. American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 619-899-6109; e-mail customersrvc@acers.org; www.ceramics.org.

20-25 202nd Meeting of the Electrochemical Society, *Salt Lake City, UT*. The Electrochemical Society, 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org.

29-3 ABET Annual Meeting, *Pittsburgh, PA*. 2002 ABET Annual Meeting, 11 Market Place, Ste. 1050, Baltimore, MD 21202-4012; www.abet.org.

NOVEMBER 2002

11-15 44th Annual Meeting of the APS Division of Plasma Physics, *Orlando, FL*. American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

DECEMBER 2002

2-6 MRS Fall Meeting, *Boston, MA*. Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS.**

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